

FIG. 1A

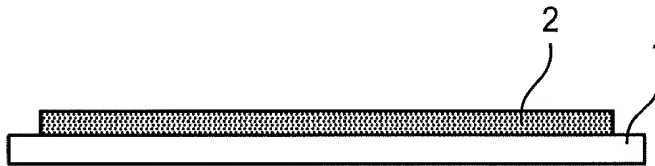
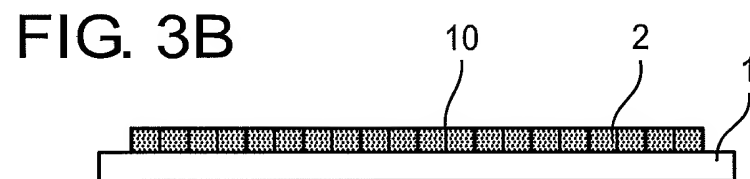
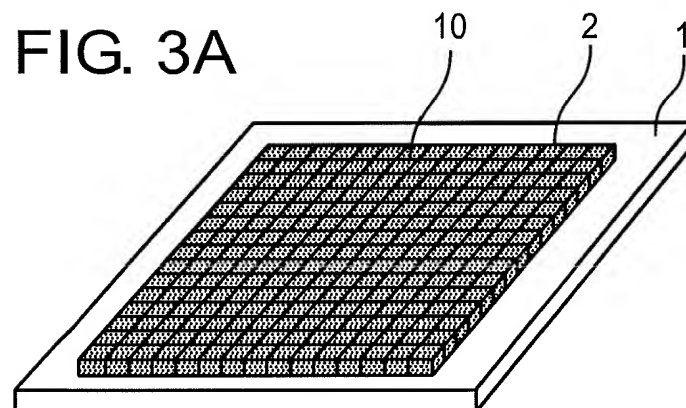
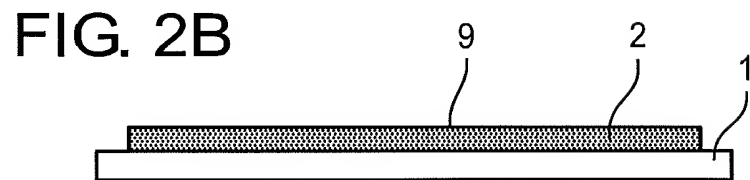
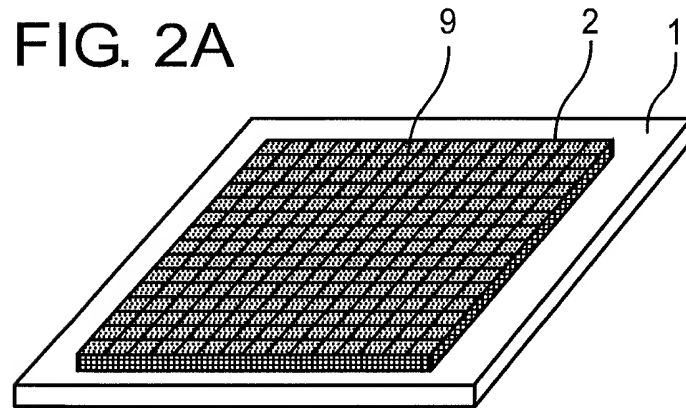
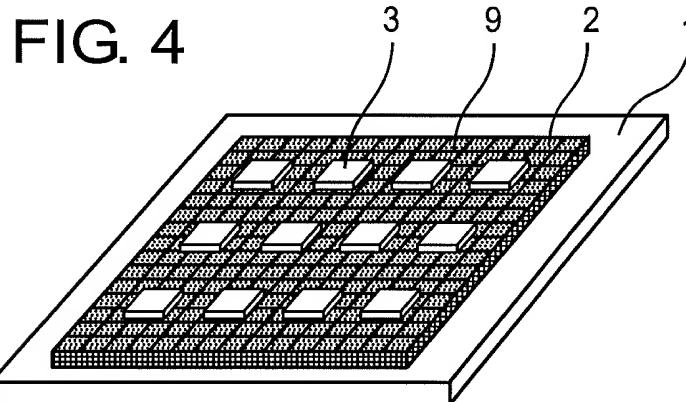


FIG. 1B





SUBSTRATE MOUNTING PROCESS

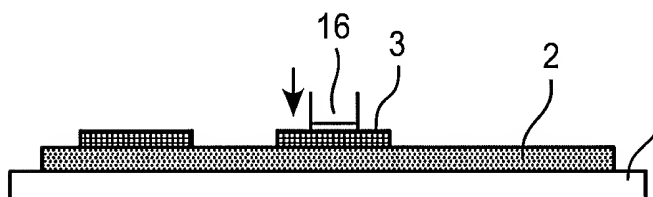


FIG. 5A

DIE BONDING PROCESS

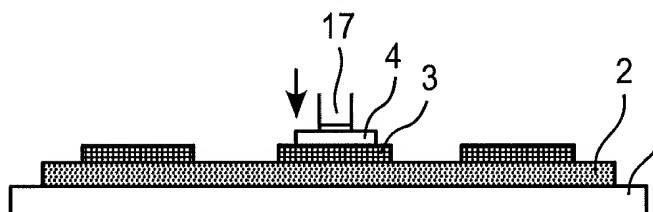


FIG. 5B

WIRE BONDING PROCESS

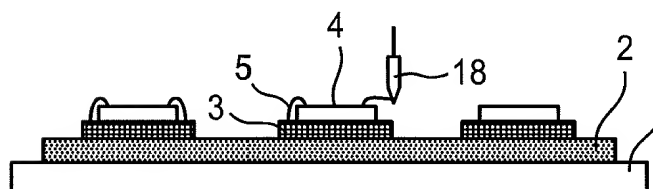


FIG. 5C

SUBSTRATE MOUNTING PROCESS

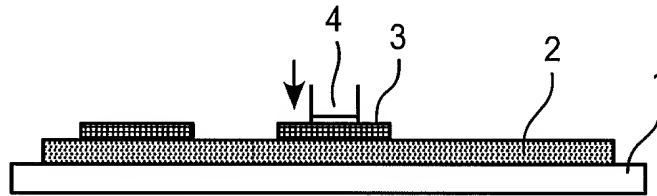


FIG. 6A

BUMP BONDING PROCESS

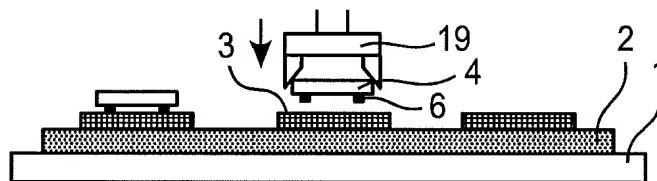


FIG. 6B

Prior Art
FIG. 7

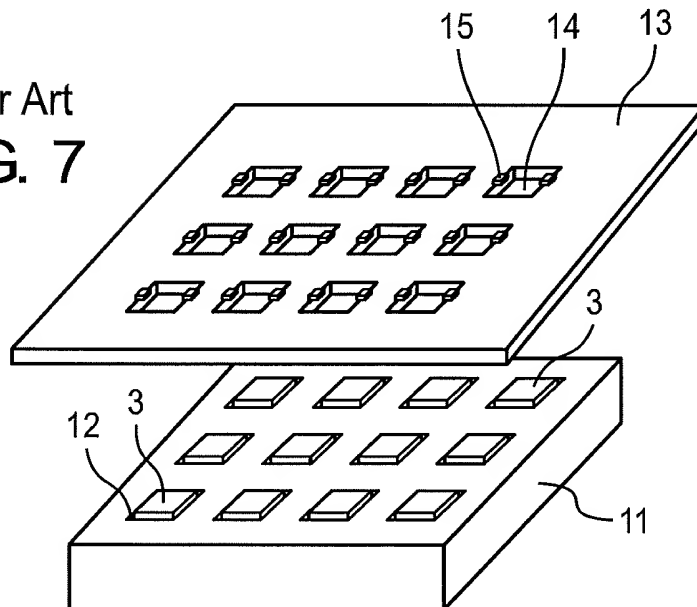
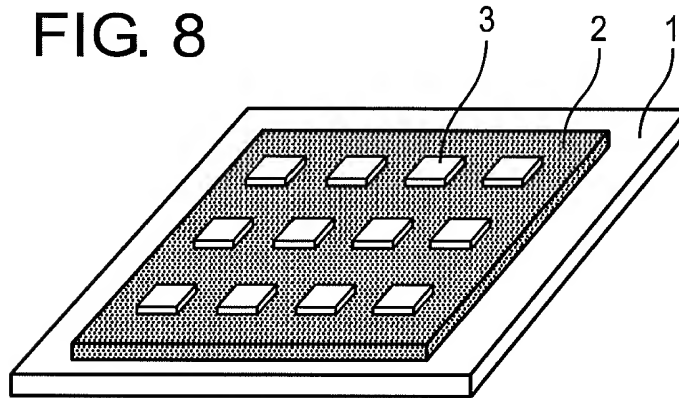


FIG. 8



SUBSTRATE MOUNTING PROCESS

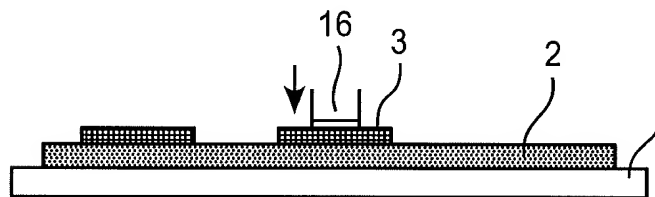


FIG. 9A

DIE BONDING PROCESS

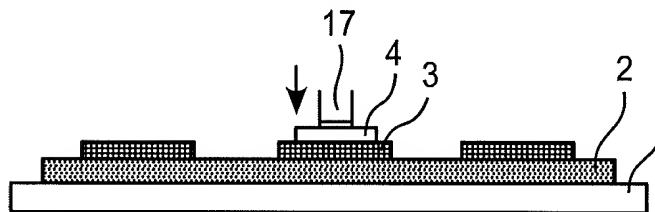


FIG. 9B

WIRE BONDING PROCESS

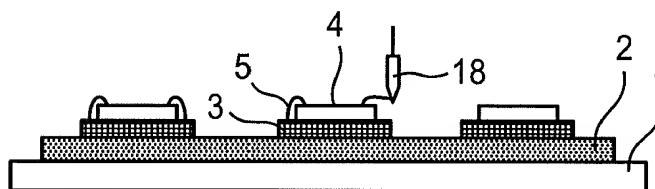


FIG. 9C

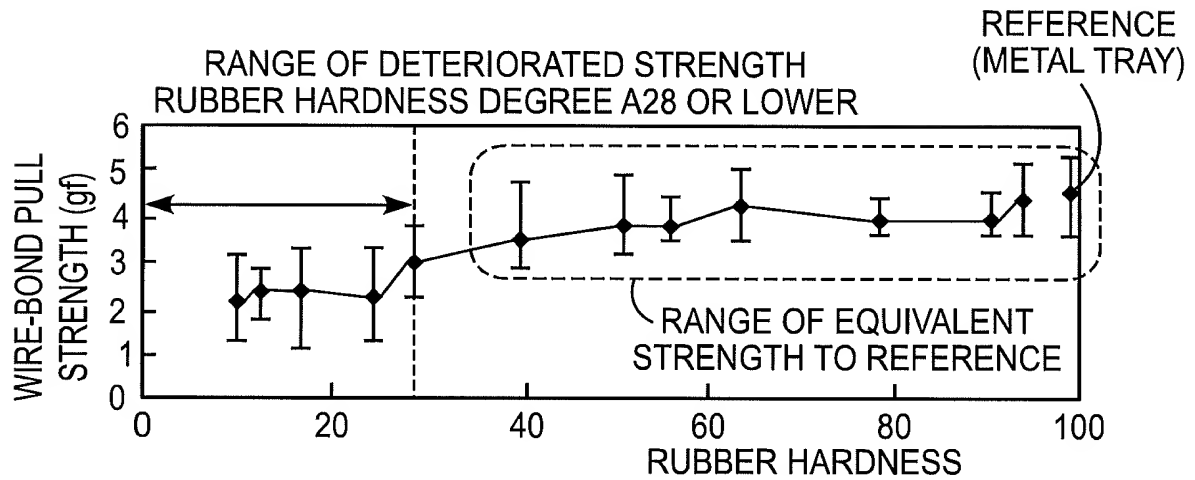


FIG. 10

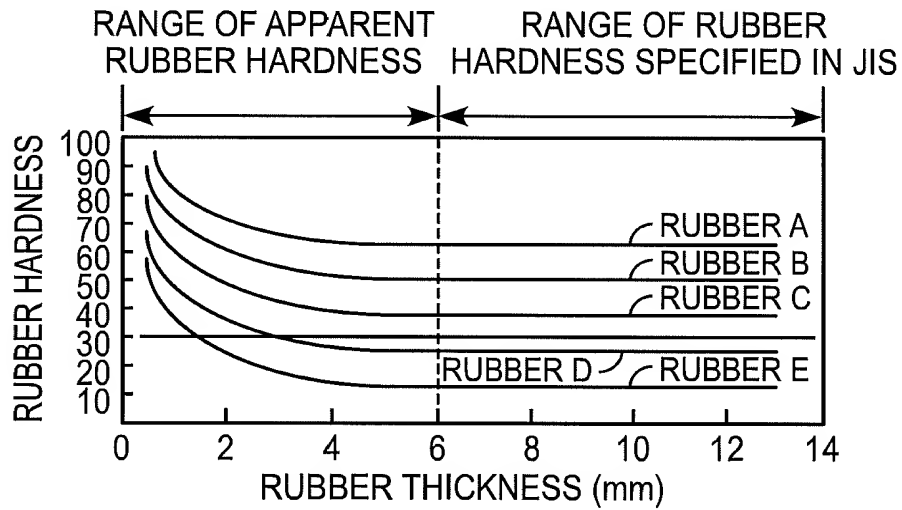


FIG. 11

